

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. **(Canceled)**
2. **(Canceled)**
3. **(Previously Presented)** A substrate processing apparatus for processing a substrate with a plurality of processing solutions having different components, comprising:
 - a holding element provided on a rotating base, for holding a peripheral portion of a substrate to keep said substrate in a substantially-horizontal position;
 - a rotation element for rotating said substrate held by said holding element about an axis along a substantially-vertical direction;
 - an atmosphere cutoff plate positioned above said holding element, facing a top surface of said substrate held by said holding element; and
 - a splash prevention element for receiving said plurality of processing solutions splashed from said peripheral portion of said substrate held by said holding element, wherein said splash prevention element comprises
 - a plurality of recovery ducts used for collecting said plurality of processing solutions;
 - a plurality of guiding members for forming said plurality of recovery ducts so that a vertical spacing of each opening thereof is not less than a distance between said rotating base and said atmosphere cutoff plate; and
 - a selection element for selecting one of said recovery ducts to be used for collecting a processing solution used in a processing for said substrate, to determine a selected recovery duct, wherein a level of a lower surface of a guiding member used for forming said selected recovery duct is set not lower than a level of a lower surface of said rotating base near an opening of said selected recovery duct; and
 - wherein a level of a top surface of a guiding member used for forming said selected recovery duct is set not higher than a level of a top surface of said atmosphere cutoff plate.

4. **(Previously Presented)** The substrate processing apparatus according to claim 3, wherein

said selected recovery duct has a shape curving downward, going away from a substrate with a vertical spacing almost equal to a vertical spacing of an opening thereof.

5. **(Previously Presented)** The substrate processing apparatus according to claim 3, wherein

said selected recovery duct guides one of said plurality of processing solutions downward almost around a substrate.

6. **(Previously Presented)** The substrate processing apparatus according to claim 3, further comprising

a suck element communicated with said selected recovery duct, for sucking said one of said plurality of processing solutions.

7. **(Previously Presented)** The substrate processing apparatus according to claim 3, wherein

said rotating base and said atmosphere cutoff plate each have a disk-like shape and respective edge portions thereof facing said plurality of recovery ducts are vertical slide surfaces.

8. **(Previously Presented)** The substrate processing apparatus according to claim 3, wherein

respective openings of said plurality of recovery ducts which are vertically stacked are disposed at almost the same position in a vertical direction.

9. **(New)** A substrate processing apparatus for processing a substrate with a plurality of processing solutions having different components, comprising:

a holding element provided on a rotating base, for holding a peripheral portion of a substrate to keep said substrate in a substantially-horizontal position;

a rotation element for rotating said substrate held by said holding element about an axis along a substantially-vertical direction;

an atmosphere cutoff plate positioned above said holding element, facing a top surface of said substrate held by said holding element; and

a splash prevention element for receiving said plurality of processing solutions splashed from said peripheral portion of said substrate held by said holding element,

wherein said splash prevention element comprises

a plurality of recovery ducts used for collecting said plurality of processing solutions;

a plurality of guiding members for forming said plurality of recovery ducts so that a vertical spacing of each opening thereof is not less than a distance between said rotating base and said atmosphere cutoff plate, said distance being made when any of said plurality of recovery ducts are collecting a processing solution; and

a selection element for selecting one of said recovery ducts to be used for collecting a processing solution used in a processing for said substrate, to determine a selected recovery duct,

wherein a level of said selected recovery duct is adjusted so that a level of a lower surface of a guiding member used for forming said selected recovery duct is set not lower than a level of a lower surface of said rotating base near an opening of said selected recovery duct, and

wherein said selected recovery duct is disposed so that a level of a lower surface of a guiding member for forming said selected recovery duct is not lower than a level of a lower surface of said rotating base, and said atmosphere cutoff plate is disposed so that a processing solution is collected in said selected recovery duct, then, as a result, a level of a top surface of a guiding member used for forming said selected recovery duct is set not higher than a level of a top surface of said atmosphere cutoff plate.

10. (New) The substrate processing apparatus according to claim 9, wherein said selected recovery duct has a shape curving downward, going away from a substrate with a vertical spacing almost equal to a vertical spacing of an opening thereof.

11. (New) The substrate processing apparatus according to claim 9, wherein said selected recovery duct guides one of said plurality of processing solutions downward almost around a substrate.

12. (New) The substrate processing apparatus according to claim 9, further comprising
a suck element communicated with said selected recovery duct, for sucking said one of said plurality of processing solutions.

13. (New) The substrate processing apparatus according to claim 9, wherein said rotating base and said atmosphere cutoff plate each have a disk-like shape and respective edge portions thereof facing said plurality of recovery ducts are vertical side surfaces.

14. (New) The substrate processing apparatus according to claim 9, wherein respective openings of said plurality of recovery ducts which are vertically stacked are disposed at almost the same position in a vertical direction.

15. (New) A substrate processing apparatus for processing a substrate with a plurality of processing solutions having different components, comprising:

a holding element provided on a rotating base, for holding a peripheral portion of a substrate to keep said substrate in a substantially-horizontal position;

a rotation element for rotating said substrate held by said holding element about an axis along a substantially-vertical direction;

an atmosphere cutoff plate positioned above said holding element, facing a top surface of said substrate held by said holding element; and

a splash prevention element for receiving said plurality of processing solutions splashed from said peripheral portion of said substrate held by said holding element,

wherein said splash prevention element comprises

a plurality of recovery ducts used for collecting said plurality of processing solutions;

a plurality of guiding members for forming said plurality of recovery ducts; and

a selection element for selecting one of said recovery ducts to be used for collecting a processing solution used in a processing for said substrate, to determine a selected recovery duct,

wherein when processing said substrate held by said holding element with a plurality of processing solutions, said atmosphere cutoff plate is disposed at a processing position to have a predetermined distance from said rotating base, and a guiding member for forming said selected recovery duct is disposed at a collecting position,

wherein in said collecting position, a vertical spacing of an opening of said selected recovery duct is not less than said predetermined distance,

wherein a level of a lower surface of a guiding member used for forming said selected recovery duct is set not lower than a level of a lower surface of said rotating base near an opening of said selected recovery duct, and

wherein a level of a top surface of a guiding member used for forming said selected recovery duct is set not higher than a level of a top surface of said atmosphere cutoff plate at said processing position near an opening of said selected recovery duct.

16. (New) The substrate processing apparatus according to claim 15, wherein said selected recovery duct has a shape curving downward, going away from a substrate with a vertical spacing almost equal to a vertical spacing of an opening thereof.

17. (New) The substrate processing apparatus according to claim 15, wherein said selected recovery duct guides one of said plurality of processing solutions downward almost around a substrate.

18. (New) The substrate processing apparatus according to claim 15, further comprising

a suck element communicated with said selected recovery duct, for sucking said one of said plurality of processing solutions.

19. (New) The substrate processing apparatus according to claim 15, wherein said rotating base and said atmosphere cutoff plate each have a disk-like shape and respective edge portions thereof facing said plurality of recovery ducts are vertical side surfaces.

20. (New) The substrate processing apparatus according to claim 15, wherein respective openings of said plurality of recovery ducts which are vertically stacked are disposed at almost the same position in a vertical direction.